**Preferred Device** 

#### Advance Information

## Power MOSFET 6 Amps, 400 Volts

#### **N-Channel DPAK**

Designed for high voltage, high speed switching applications in power supplies, converters, power motor controls and bridge circuits.

#### **Features**

- Higher Current Rating
- Lower RDS(on)
- Lower Capacitances
- Lower Total Gate Charge
- Tighter V<sub>SD</sub> Specifications
- Avalanche Energy Specified
- Industry Standard DPAK Surface Mount Package

#### **Typical Applications**

- Switch Mode Power Supplies
- PWM Motor Controls
- Converters
- Bridge Circuits

#### **MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	400	Vdc	
Drain–Gate Voltage (RGS = 1.0 M $\Omega$ )	VDGR	400	Vdc	
Gate–Source Voltage  – Continuous  – Non–Repetitive (t <sub>p</sub> ≤10 ms)	V <sub>GS</sub> V <sub>GSM</sub>	±20 ±40	Vdc	
Drain − Continuous − Continuous @ 100°C − Single Pulse (t <sub>p</sub> ≤10 μs)	ID IDM	6.0 4.2 21	Adc	
Total Power Dissipation Derate above 25°C Total Power Dissipation @ T <sub>C</sub> = 25°C when mounted with the minimum recommended pad size	P <sub>D</sub>	96 0.77 1.75	Watts W/°C W/°C	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C	
Single Drain–to–Source Avalanche Energy – Starting T <sub>J</sub> = 25°C (V <sub>DD</sub> = 100 Vdc, V <sub>GS</sub> = 10 Vdc, I <sub>L</sub> = 6 A, L = 10 mH, R <sub>G</sub> = 25 Ω)	EAS	180	mJ	
Thermal Resistance  – Junction-to-Case  – Junction-to-Ambient  – Junction-to-Ambient (Note 1.)	$R_{ heta JC} \ R_{ heta JA} \ R_{ heta JA}$	1.30 100 71.4	°C/W	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	°C	

 When surface mounted to an FR4 board using the minimum recommended pad size.

This document contains information on a new product. Specifications and information herein are subject to change without notice.



#### **ON Semiconductor**

http://onsemi.com

### 6 AMPERES 400 VOLTS RDS(on) = 1100 m $\Omega$

# N-Channel Do

#### MARKING DIAGRAMS

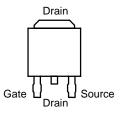


CASE 369A DPAK STYLE 2



Y = Year WW = Work Week T = MOSFET

#### **PIN ASSIGNMENT**



#### **ORDERING INFORMATION**

Device	Package	Shipping	
NTD6N40	DPAK	75 Units/Rail	
NTD6N40-1	DPAK	75 Units/Rail	
NTD6N40T4	DPAK	2500 Tape & Reel	

**Preferred** devices are recommended choices for future use and best overall value.

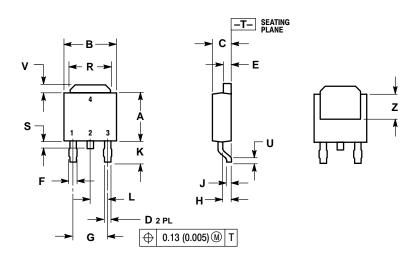
#### **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

CI	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Vo (VGS = 0 Vdc, I <sub>D</sub> = 0.25 mAo Temperature Coefficient (Pos	V(BR)DSS	400 _	_ 500	_ _	Vdc mV/°C	
Zero Gate Voltage Collector Cu (V <sub>DS</sub> = 400 Vdc, V <sub>GS</sub> = 0 Vc (V <sub>DS</sub> = 400 Vdc, V <sub>GS</sub> = 0 Vc	IDSS	_ _	- -	10 100	μAdc	
Gate-Body Leakage Current (V	IGSS(f) IGSS(r)	_ _	_ _	100 100	nAdc	
ON CHARACTERISTICS (Note 2	2.)					
Gate Threshold Voltage ID = 0.25 mA, VDS = VGS Temperature Coefficient (Neg	VGS(th)	2.0	2.7 6.0	4.0 -	Vdc mV/°C	
Static Drain-to-Source On-Res	sistance (V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 3 Adc)	R <sub>DS(on)</sub>	-	900	1100	mOhm
Drain-to-Source On-Voltage (VGS = 10 Vdc, I <sub>D</sub> = 6 Adc) (V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 3 Adc, T	V <sub>DS(on)</sub>	_ _	- -	7.9 6.9	Vdc	
Forward Transconductance (V	9FS	2.0	4.4	-	mhos	
DYNAMIC CHARACTERISTICS						
Input Capacitance		C <sub>iss</sub>	-	515	720	pF
Output Capacitance	$(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}, f = 1.0 \text{ MHz})$	C <sub>oss</sub>	-	185	260	
Transfer Capacitance		C <sub>rss</sub>	-	15	30	
SWITCHING CHARACTERISTIC	<b>CS</b> (Note 3.)					
Turn-On Delay Time		<sup>t</sup> d(on)	-	7.0	10	ns
Rise Time	$(V_{DD} = 200 \text{ Vdc}, I_{D} = 6 \text{ Adc}, V_{GS} = 10 \text{ Vdc},$	t <sub>r</sub>	-	11	20	
Turn-Off Delay Time	$R_G = 9.1 \Omega$	td(off)	-	19	40	
Fall Time		t <sub>f</sub>	-	10	20	
Gate Charge		QT	-	9.5	19	nC
	$(V_{DS} = 320 \text{ Vdc}, I_{D} = 6 \text{ Adc}, V_{GS} = 10 \text{ Vdc})$	Q <sub>1</sub>	-	2.0	-	- - -
		Q <sub>2</sub>	-	3.0	-	
		Q <sub>3</sub>	-	6.0	-	
SOURCE-DRAIN DIODE CHAR	ACTERISTICS					
Forward On–Voltage (Note 2.)	$(I_S = 6 \text{ Adc}, V_{GS} = 0 \text{ Vdc})$ $(I_S = 6 \text{ Adc}, V_{GS} = 0 \text{ Vdc}, T_J = 125^{\circ}\text{C})$	V <sub>SD</sub>	_ _	0.9 0.8	1.0	Vdc
Reverse Recovery Time		t <sub>rr</sub>	_	270	_	ns
		ta	_	110	_	
	$(I_S = 6 \text{ Adc}, V_{GS} = 0 \text{ Vdc}, \\ dis/dt = 100 \text{ A/}\mu s)$	t <sub>b</sub>	_	160	_	
Reverse Recovery Stored Charge	2.0 2.1 100.1440)	Q <sub>RR</sub>	_	1.6	-	μС

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperature.

#### **PACKAGE DIMENSIONS**

#### DPAK CASE 369A-13 **ISSUE AA**



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.250	5.97	6.35	
В	0.250	0.265	6.35	6.73	
C	0.086	0.094	2.19	2.38	
D	0.027	0.035	0.69	0.88	
Е	0.033	0.040	0.84	1.01	
F	0.037	0.047	0.94	1.19	
G	0.180 BSC		4.58 BSC		
Н	0.034	0.040	0.87	1.01	
J	0.018	0.023	0.46	0.58	
K	0.102	0.114	2.60	2.89	
٦	0.090 BSC		2.29 BSC		
R	0.175	0.215	4.45	5.46	
S	0.020	0.050	0.51	1.27	
U	0.020		0.51		
٧	0.030	0.050	0.77	1.27	
Z	0.138		3.51		

- STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

#### **PUBLICATION ORDERING INFORMATION**

#### NORTH AMERICA Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

**Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

Fax Response Line: 303-675-2167 or 800-344-3810 Toll Free USA/Canada

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

EUROPE: LDC for ON Semiconductor - European Support

German Phone: (+1) 303-308-7140 (Mon-Fri 2:30pm to 7:00pm CET)

Email: ONlit-german@hibbertco.com

French Phone: (+1) 303–308–7141 (Mon–Fri 2:00pm to 7:00pm CET)

Email: ONlit-french@hibbertco.com

English Phone: (+1) 303–308–7142 (Mon–Fri 12:00pm to 5:00pm GMT)

Email: ONlit@hibbertco.com

EUROPEAN TOLL-FREE ACCESS\*: 00-800-4422-3781

\*Available from Germany, France, Italy, UK, Ireland

#### CENTRAL/SOUTH AMERICA:

Spanish Phone: 303-308-7143 (Mon-Fri 8:00am to 5:00pm MST)

Email: ONlit-spanish@hibbertco.com

Toll–Free from Mexico: Dial 01–800–288–2872 for Access –

then Dial 866-297-9322

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support

Phone: 303-675-2121 (Tue-Fri 9:00am to 1:00pm, Hong Kong Time)

Toll Free from Hong Kong & Singapore:

001-800-4422-3781 Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center

4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031 **Phone**: 81–3–5740–2700

**Email**: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local

Sales Representative.